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## Patent Abstracts of Japan

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TITLE : EPOXY RESIN COMPOSITION AND RESIN-SEALED TYPE SEMICONDUCTOR  
DEVICE

ABSTRACT : PROBLEM TO BE SOLVED: To obtain an epoxy resin composition for semiconductor  
sealing, having excellent flame retardance and reliability of moisture resistance without  
using a halogen-based flame retardant or an antimony-based flame retardant and to  
provide a resin-sealed semiconductor device.

SOLUTION: This resin composition comprises (A) an epoxy resin, (B) a curing agent, (C)  
a curing promoter, (D) an inorganic filler, (E) a particle obtained by coating the surface of  
red phosphorus with at least one kind of aluminum hydroxide and a phenol resin, (F) a  
nitrogen atom-containing compound, (G) an inorganic compound containing at least one  
kind of a first group consisting of low-melting glass powder, zinc stannate, zinc  
hydroxystannate, zinc molybdate and molybdenum trioxide.

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